

# 4A, 100V - 200V Ultra Fast Surface Mount Rectifier

#### **FEATURES**

- Planar technology
- Low power loss, high efficiency
- Ideal for automated placement
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

### **APPLICATIONS**

- High frequency switching
- DC/DC
- Snubber

#### **MECHANICAL DATA**

- Case: DO-214AB (SMC)
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.200g (approximately)

KEY PARAMETERS			
PARAMETER	VALUE	UNIT	
I <sub>F</sub>	4	Α	
$V_{RRM}$	100 - 200	V	
I <sub>FSM</sub>	130	Α	
T <sub>J MAX</sub>	175	°C	
Package	DO-214AB (SMC)		
Configuration	Single die		









**DO-214AB (SMC)** 



PARAMETER		SYMBOL	PE4BC	PE4DC	UNIT
Marking code on the device			PE4BC	PE4DC	
Repetitive peak reverse voltage		$V_{RRM}$	100	200	V
Reverse voltage, total rms value		V <sub>R(RMS)</sub>	70	140	V
Forward current		I <sub>F</sub>	4		А
Surge peak forward current single half sine-wave superimposed on rated load	t = 8.3ms		130		
	t = 1.0ms	I <sub>FSM</sub>	3	00	A
Junction temperature		T <sub>J</sub>	-55 to +175		°C
Storage temperature		T <sub>STG</sub>	-55 to +175		°C



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THERMAL PERFORMANCE				
PARAMETER	SYMBOL	TYP	UNIT	
Junction-to-lead thermal resistance	$R_{\Theta JL}$	15	°C/W	
Junction-to-ambient thermal resistance	$R_{\Theta JA}$	56	°C/W	
Junction-to-case thermal resistance	R <sub>eJC</sub>	15	°C/W	

Thermal Performance Note: Units mounted on PCB (16mm x 16mm Cu pad test board)

PARAMETER	CONDITIONS	SYMBOL	TYP	MAX	UNIT
Forward voltage <sup>(1)</sup>	$I_F = 2A, T_J = 25^{\circ}C$		0.80	-	V
	I <sub>F</sub> = 3A, T <sub>J</sub> = 25°C	,,	0.83	0.90	V
	I <sub>F</sub> = 4A, T <sub>J</sub> = 25°C		0.86	0.93	V
	I <sub>F</sub> = 2A, T <sub>J</sub> = 125°C	V <sub>F</sub>	0.63	-	V
	I <sub>F</sub> = 3A, T <sub>J</sub> = 125°C		0.67	-	V
	I <sub>F</sub> = 4A, T <sub>J</sub> = 125°C		0.71	-	V
Deverge correct @ reted \/ (2)	T <sub>J</sub> = 25°C		-	2	μA
Reverse current @ rated V <sub>R</sub> (2)	T <sub>J</sub> = 125°C	- I <sub>R</sub>	-	10	μA
Junction capacitance	1MHz, V <sub>R</sub> = 4.0V	CJ	72	-	pF
Davaraa raaayany tima	I <sub>F</sub> = 0.5A, I <sub>R</sub> = 1.0A, I <sub>rr</sub> = 0.25A	_	-	20	ns
Reverse recovery time	$I_F = 1.0A$ , di/dt = 50A/ $\mu$ s, $V_R = 30V$	t <sub>rr</sub>	22	-	
Reverse recovery current		I <sub>RM</sub>	2.9	-	Α
Reverse recovery charge	$I_F = 4.0A$ , di/dt = 200A/ $\mu$ s, $V_R = 100V$	Q <sub>rr</sub>	25.4	-	nC
Reverse recovery time		t <sub>rr</sub>	16.4	-	ns

# Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

ORDERING INFORMATION		
ORDERING CODE <sup>(1)</sup>	PACKAGE	PACKING
PE4xC	DO-214AB (SMC)	3,000/ Tape & Reel

### Notes:

1. "x" defines voltage from 100V(PE4BC) to 200V(PE4DC)



#### **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

**Fig.1 Forward Current Derating Curve** 

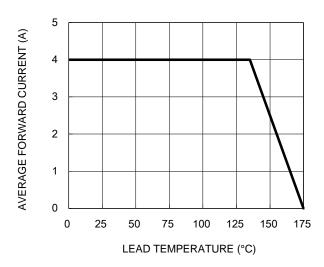


Fig.3 Typical Reverse Characteristics

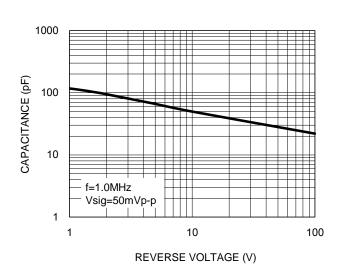
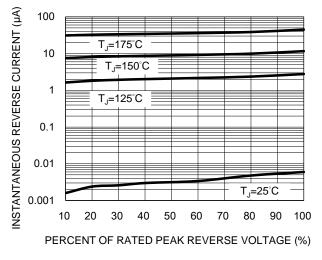


Fig.2 Typical Junction Capacitance

**Fig.4 Typical Forward Characteristics** 



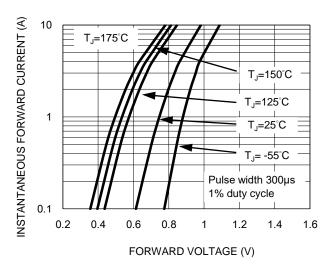
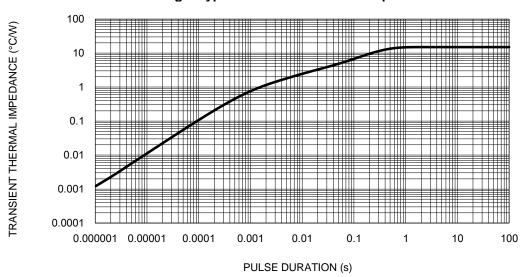


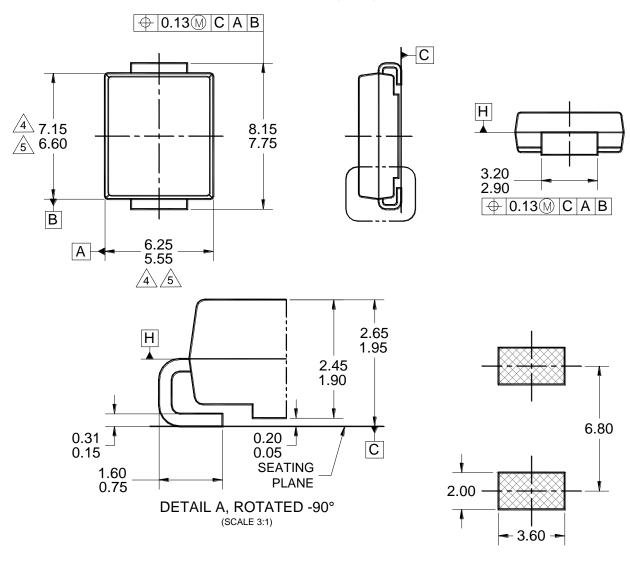
Fig.5 Typical Transient Thermal Impedance

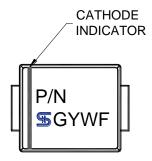




#### **PACKAGE OUTLINE DIMENSIONS**

## **DO-214AB (SMC)**





#### MARKING DIAGRAM

P/N = MARKING CODE

G = GREEN COMPOUND

YW = DATE CODE

F = FACTORY CODE

## NOTES: UNLESS OTHERWISE SPECIFIED

1. ALL DIMENSIONS ARE IN MILLIMETERS.

SUGGESTED PAD LAYOUT

- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- 3. PACKAGE OUTLINE REFERENCE: JEDEC DO-214, VARIATION AB, ISSUE D.
- MOLDED PLASTIC BODY DIMENSIONS DO NOT INCLUDE MOLD FLASH.
- MOLDED PLASTIC BODY LATERAL DIMENSIONS TO BE DETERMINED AT DATUM PLANE H.
- 6. DWG NO. REF: HQ2SD07-DO214SMC-036 REV A.



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